

## Single N-Channel MOSFET

### ■ DESCRIPTION

SMC3404 is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss are needed in small outline surface mount package.

### ■ PART NUMBER INFORMATION

**SMC 3404 S - TR G**  
 a b c d e

a : Company name.

b : Product Serial number.

c : Package code            S: SOT-23L

d : Handling code        TR: Tape&Reel

e : Green produce code G: *RoHS Compliant*

### ■ FEATURES

**$V_{DS} = 30V, \quad I_D = 6.7A$**

$R_{DS(ON)}=18m\Omega(\text{Typ.}) @ V_{GS}=10V$

$R_{DS(ON)}=23m\Omega(\text{Typ.}) @ V_{GS}=4.5V$

◆Fast switch

◆Low gate drive applications

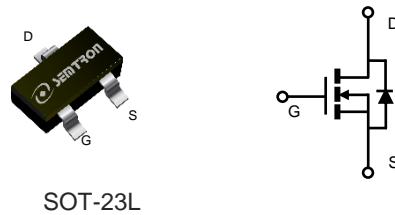
◆High power and current handling capability

### ■ APPLICATIONS

◆Power Management in Note book

◆Portable Equipment

◆DC/DC Converter



SOT-23L

### ■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current $T_A=25^\circ C$	6.7	A
		$T_A=70^\circ C$	A
$I_{DM}$	Pulsed Drain Current <sup>A</sup>	26.8	A
$P_D$	Power Dissipation <sup>B</sup> $T_A=25^\circ C$	1.6	W
		$T_A=70^\circ C$	W
$T_J$	Operation Junction Temperature	-55/150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ C$

### ■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>B</sup> $t \leq 10s$		80	$^\circ C/W$
	Thermal Resistance Junction to Ambient <sup>BC</sup> Steady-State		120	

**ELECTRICAL CHARACTERISTICS( $T_A = 25^\circ\text{C}$  Unless otherwise noted)**

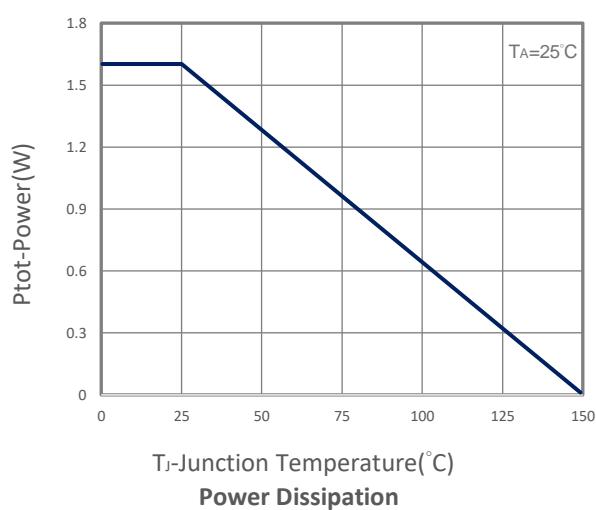
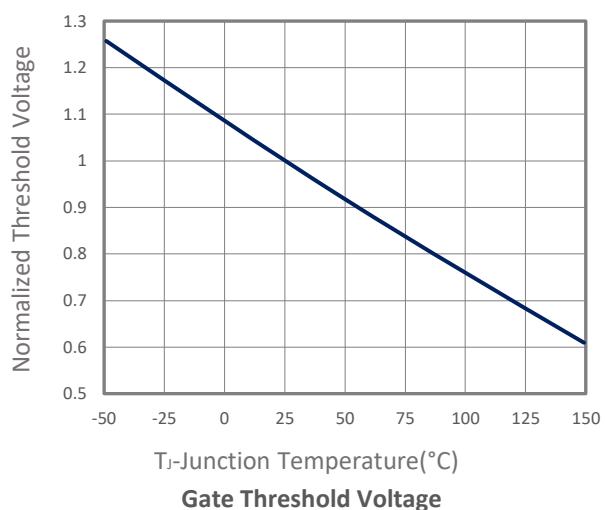
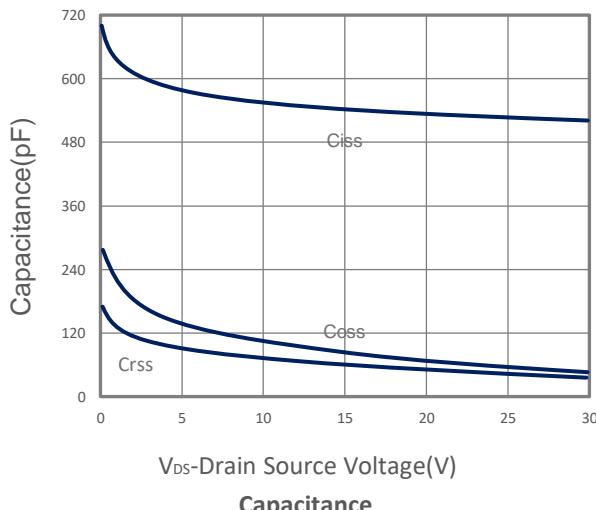
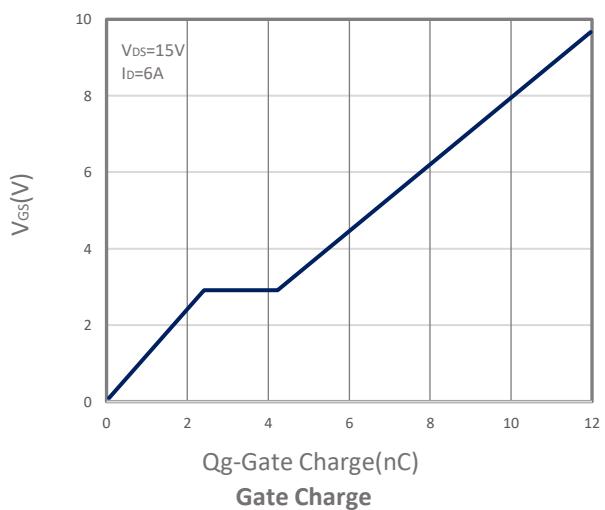
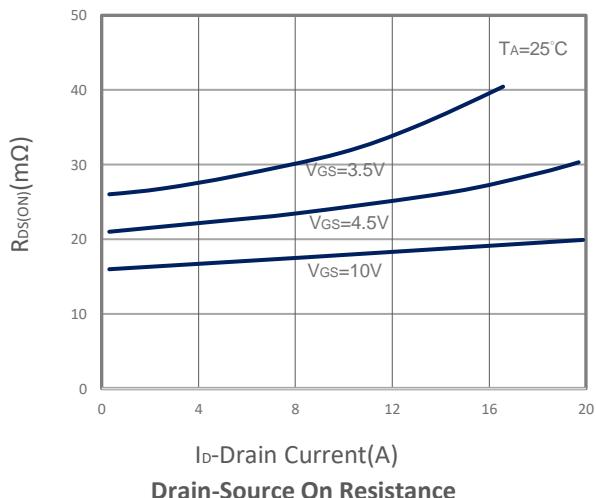
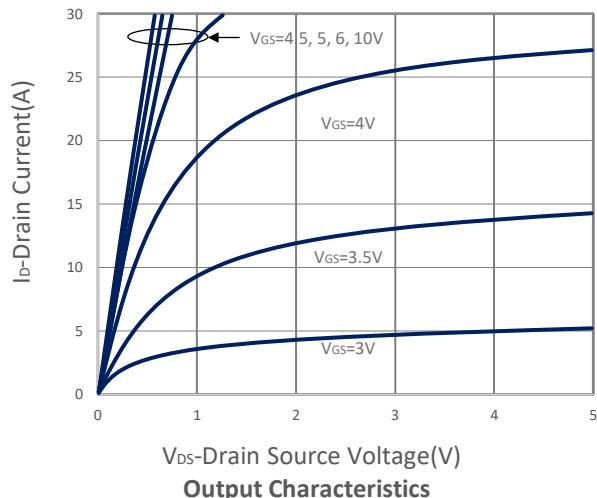
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
<b>Static Parameters</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.5	2	V	
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			$\pm 100$	nA	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$		1		$\mu\text{A}$	
		$V_{DS}=24\text{V}, V_{GS}=0\text{V}, T_J=75^\circ\text{C}$		10			
$R_{DS(\text{ON})}$	Drain-source On-Resistance	$V_{GS}=10\text{V}, I_D=6.7\text{A}$		18	22	$\text{m}\Omega$	
		$V_{GS}=4.5\text{V}, I_D=4.8\text{A}$		23	30		
		$V_{GS}=3.5\text{V}, I_D=2\text{A}$		27	34		
$G_f$	Forward Transconductance	$V_{DS}=15\text{V}, I_D=6\text{A}$		6		S	
<b>Diode Characteristics</b>							
$V_{SD}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.7	1.0	V	
$I_S$	Continuous Source Current				6.7	A	
$t_{rr}$	Reverse Recovery Time	$I_S=6\text{A}, dI/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$		20		ns	
$Q_{rr}$	Reverse Recovery Charge			1.2		nC	
<b>Dynamic and Switching Parameters</b>							
$Q_g$	Total Gate Charge	$V_{DS}=15\text{V}, V_{GS}=10\text{V}, I_D=6\text{A}$		12.7	17.8	nC	
$Q_g$	Total Gate Charge(4.5V)			6.2	8.7		
$Q_{gs}$	Gate-Source Charge			2.4	3.4		
$Q_{gd}$	Gate-Drain Charge			2	2.8		
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		550		pF	
$C_{oss}$	Output Capacitance			78			
$C_{rss}$	Reverse Transfer Capacitance			62			
$R_g$	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, F=1\text{MHz}$		2.4		$\Omega$	
$t_{d(on)}$	Turn-On Time	$V_{DD}=15\text{V}, V_{GEN}=10\text{V}, R_G=6\Omega, I_D=1\text{A}$		2.5	5	nS	
				7.6	14		
$t_{d(off)}$	Turn-Off Time			19.8	38		
$t_f$				4.2	8		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

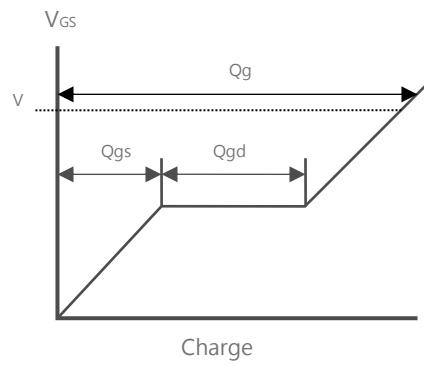
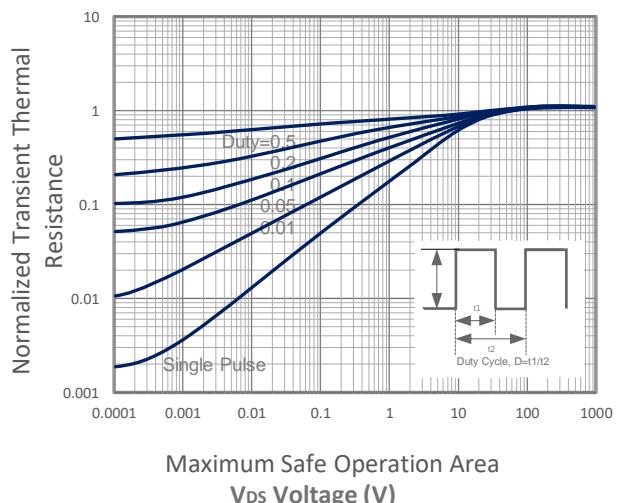
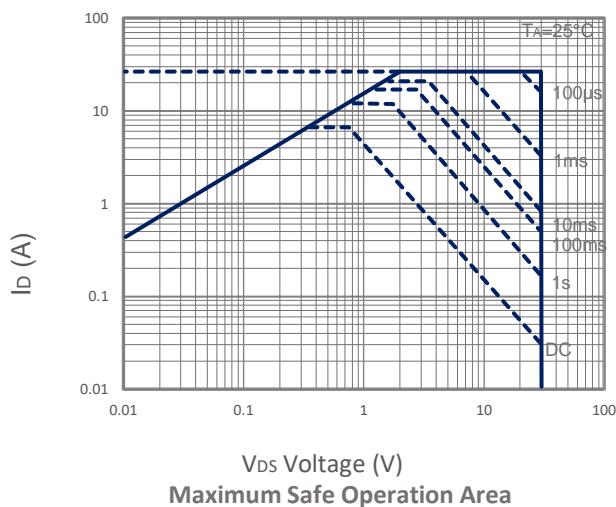
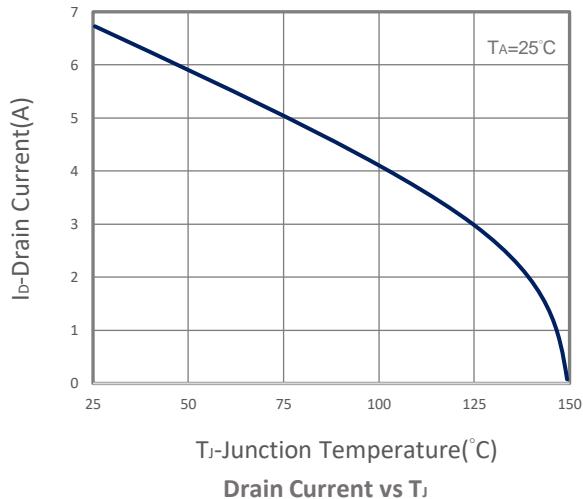
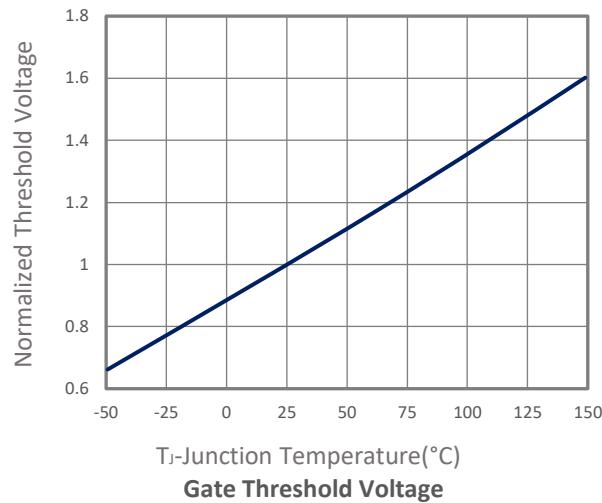
- A. Pulsed width limited by maximum junction temperature,  $T_J(\text{MAX})=150^\circ\text{C}$ .
- B. Measure the value in a still air environment at  $T_A=25^\circ\text{C}$ , using an installation mounted on a 1 in2 FR-4 board, maximum junction temperature  $T_J(\text{MAX})=150^\circ\text{C}$ .
- C.  $T_J(\text{MAX})=150^\circ\text{C}$ , using junction-to-case thermal resistance ( $R_{\thetaJC}$ ) is more useful in additional heat sinking is used.

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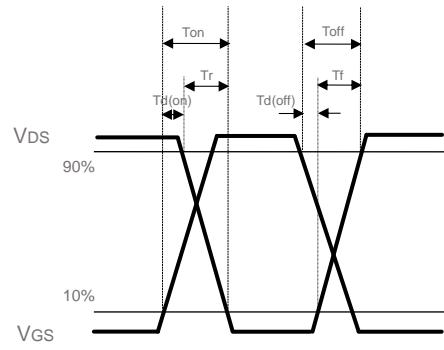
## TYPICAL CHARACTERISTICS



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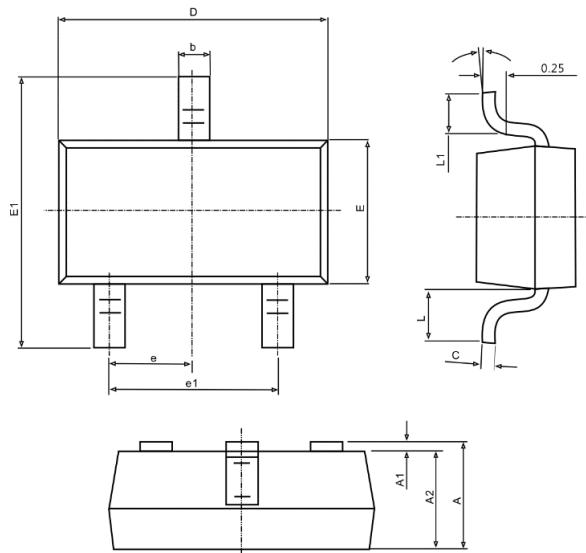


Gate Charge Waveform

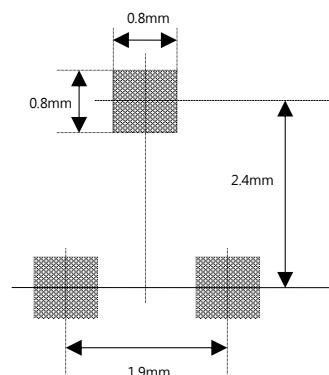


Switching Time Waveform

## SOT-23L PACKAGE DIMENSIONS



Recommended Minimum Pad(mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.000	1.300	0.039	0.049
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.039	0.047
b	0.300	0.500	0.012	0.020
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E	1.500	1.700	0.059	0.067
E1	2.600	3.000	0.102	0.118
e	0.950 TYP.		0.037 TYP.	
e1	1.900 TYP.		0.075 TYP.	
L1	0.250	0.550	0.010	0.022
θ	0°	8°	0°	8°